



DUAL N-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

Device	BV _{DSS}	R _{DS(ON)} Max	I _{D Max} T _A = +25°C
	2017	$35m\Omega$ @ $V_{GS} = 4.5V$	4.6A
N-Channel	20V	$43m\Omega$ @ $V_{GS} = 2.5V$	4.2A

Features

- PCB Footprint of 4mm²
- Low On-Resistance
- Low Input Capacitance
- Low Profile, 0.6mm Maximum Height
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen- and Antimony-Free. "Green" Device (Note 3)
- The DMN2053UFDBQ is suitable for automotive applications requiring specific change control; This part is AEC-Q101 qualified, PPAP capable, and manufactured in IATF 16949 certified facilities.

https://www.diodes.com/quality/product-definitions/

Description and Applications

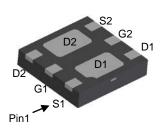
This MOSFET is designed to minimize the on-state resistance (R_{DS(ON)}) yet maintain superior switching performance, which makes it ideal for high-efficiency power management applications.

- Load Switch
- Power Management Functions
- Portable Power Adaptors

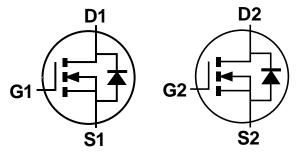
Mechanical Data

- Case: U-DFN2020-6
- Case Material: Molded Plastic, "Green" Molding Compound.
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish NiPdAu over Copper Lead-Frame. Solderable per MIL-STD-202, Method 208
- Terminals Connections: See Diagram Below
- Weight: 0.0065 grams (Approximate)

U-DFN2020-6 (Type B)



Bottom View



Internal Schematic

Ordering Information (Note 4)

Part Number	Case	Packaging
DMN2053UFDBQ-7	U-DFN2020-6 (Type B)	3,000/Tape & Reel
DMN2053UFDBQ-13	U-DFN2020-6 (Type B)	10,000/Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/



Marking Information

U-DFN2020-6 (Type B)



H5 = Product Type Marking Code YWX = Date Code Marking Y = Year (ex: 0 = 2020) W = Week (ex: a = Week 27; z Represents Week 52 and 53) X = Internal Code (ex: U = Monday)

Date Code Key

Year	2020	2021	2022	2023	2024	2025	2026	2027	2028	2029	2030	2031
Code	0	1	2	3	4	5	6	7	8	9	0	1

Week	1-26	27-52	53
Code	A-Z	a-z	Z

Internal Code	Sun	Mon	Tue	Wed	Thu	Fri	Sat
Code	Т	U	V	W	Χ	Υ	Z



Maximum Ratings (@ T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Drain-Source Voltage	V _{DSS}	20	V
Gate-Source Voltage	V_{GSS}	±12	V
Continuous Drain Current (Note 6) V _{GS} = 4.5V	I _D	4.6 3.7	А
Maximum Continuous Body Diode Forward Current (Note 6	Is	1.1	А
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)	I _{DM}	24	Α

Thermal Characteristics

Characteristic		Symbol	Value	Unit
Total Power Dissipation (Note 5)	$T_A = +25$ °C	P_{D}	0.82	W
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	$R_{\theta JA}$	153	°C/W
Total Power Dissipation (Note 6)	$T_A = +25^{\circ}C$	P _D	1.14	W
Thermal Resistance, Junction to Ambient (Note 6)	Steady State	$R_{\theta JA}$	110	°C/W
Operating and Storage Temperature Range		$T_{J_i}T_{STG}$	-55 to +150	°C

Electrical Characteristics (@ T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 7)						
Drain-Source Breakdown Voltage	BV _{DSS}	20	_	_	V	$V_{GS} = 0V, I_D = 250\mu A$
Zero Gate Voltage Drain Current T _J = +25°C	I _{DSS}	_	_	1.0	μΑ	$V_{DS} = 20V, V_{GS} = 0V$
Gate-Source Leakage	I _{GSS}		_	±10	μΑ	$V_{GS} = \pm 12V, V_{DS} = 0V$
ON CHARACTERISTICS (Note 7)						
Gate Threshold Voltage	V _{GS(TH)}	0.4	_	1.0	V	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$
			_	35		$V_{GS} = 4.5V, I_D = 5A$
Static Drain-Source On-Resistance	R _{DS(ON)}	_	_	43	mΩ	V _{GS} = 2.5V, I _D = 4A
			_	56		$V_{GS} = 1.8V, I_D = 2A$
Diode Forward Voltage	V_{SD}	<u> </u>	_	1.2	V	$V_{GS} = 0V, I_{S} = 1A$
DYNAMIC CHARACTERISTICS (Note 8)						
Input Capacitance	C _{iss}	_	369	_		12/1/
Output Capacitance	Coss	_	54		pF	$V_{DS} = 10V, V_{GS} = 0V,$ f = 1.0MHz
Reverse Transfer Capacitance	C _{rss}	_	32			= 1.0 V
Gate Resistance	R_g	_	4.1	_	Ω	$V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1MHz$
Total Gate Charge (V _{GS} = 4.5V)	Qg	_	3.6	_		
Total Gate Charge (V _{GS} = 10V)	Qg	_	7.7		nC	V _{DS} = 10V. I _D = 6A
Gate-Source Charge	Q _{gs}	_	0.4	_	110	V _{DS} = 10V, I _D = 0A
Gate-Drain Charge	Q _{gd}	_	1.0			
Turn-On Delay Time	t _{D(ON)}	_	2.6	_		
Turn-On Rise Time	t _R	_	3.0		ns	$V_{DS} = 10V, V_{GS} = 4.5V,$
Turn-Off Delay Time	t _{D(OFF)}	_	12.5	_	115	$R_g = 6\Omega$, $R_L = 10\Omega$, $I_D = 6A$
Turn-Off Fall Time	t _F	_	3.6			
Reverse Recovery Time	t _{RR}	_	6.0	_	ns	I _F = 1A, di/dt = 100A/μs
Reverse Recovery Charge	Q _{RR}		0.9	_	nC	I _F = 1A, di/dt = 100A/μs

Notes: 5. Device mounted on FR-4 substrate PCB, 2oz copper, with minimum recommended pad layout.

Device mounted on FR-4 substrate PCB, 2oz copper, with 1inch square copper plate.
 Short duration pulse test used to minimize self-heating effect.

Short duration purse test used to minimize sent-reating e
 Sugaranteed by design. Not subject to product testing.



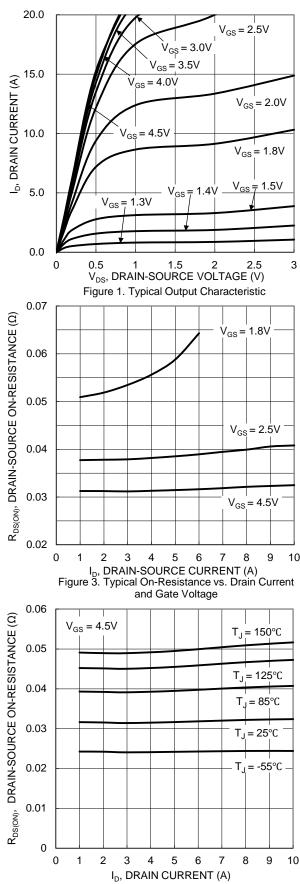
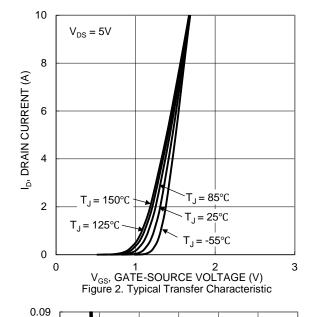
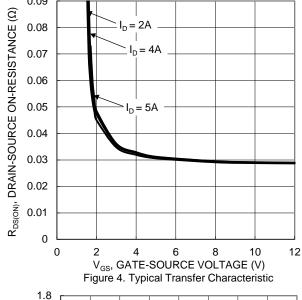


Figure 5. Typical On-Resistance vs. Drain Current and Junction Temperature





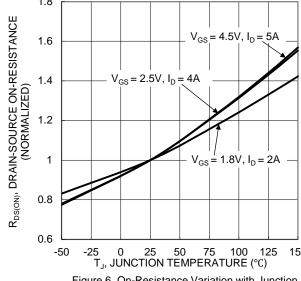
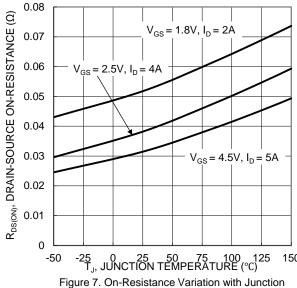
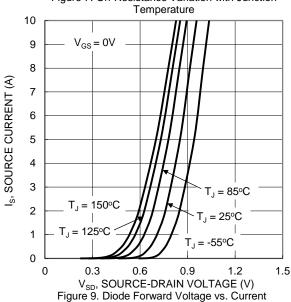


Figure 6. On-Resistance Variation with Junction Temperature







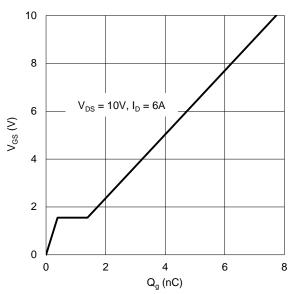
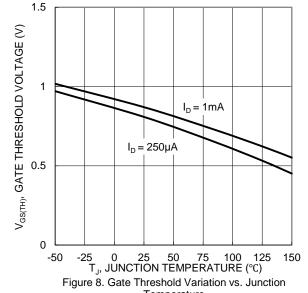
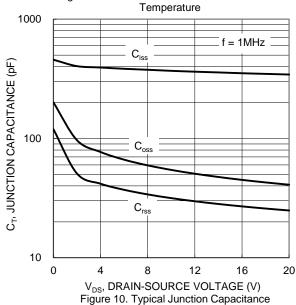
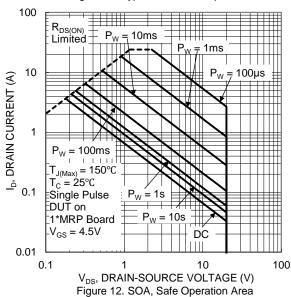


Figure 11. Gate Charge









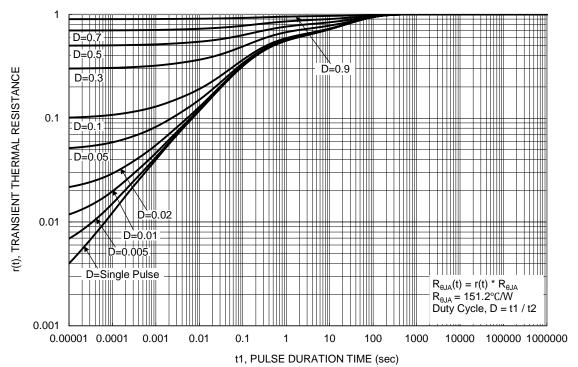
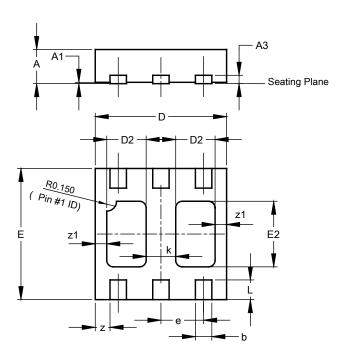


Figure 13. Transient Thermal Resistance



Package Outline Dimensions

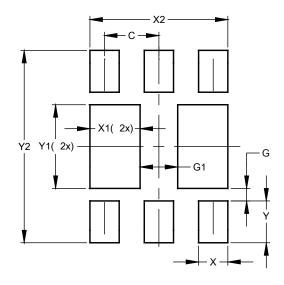
Please see http://www.diodes.com/package-outlines.html for the latest version.



U-DFN2020-6							
Type B							
Dim	Dim Min Max						
Α	0.545	0.605	0.575				
A1	0.00	0.05	0.02				
A3	_	_	0.13				
b	0.20	0.30	0.25				
D	1.95	2.075	2.00				
D2	0.50	0.70	0.60				
е	-	-	0.65				
Е	1.95	2.075	2.00				
E2	0.90	1.10	1.00				
k	_	_	0.45				
L	0.25	0.35	0.30				
z	_	_	0.225				
z1		_	0.175				
All	Dimens	ions in	mm				

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.



Dimensions	Value (in mm)
С	0.650
G	0.150
G1	0.450
Х	0.350
X1	0.600
X2	1.650
Y	0.500
Y1	1.000
Y2	2.300



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